# THE 20TH IEEE INTERNATIONAL CONFERENCE ON INDUSTRIAL TECHNOLOGY
# IEEE-ICIT 2019

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### Special Session on

## "Wireless Sensor Networks: Hardware/Software Design Aspects for Industry"

# Organized by

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## Call for Papers

After organizing 8 special sessions at IES Conferences, we have decided to organize the 9th session at ICIT 2019.

The aim of this special session is to address the current and the new developments of wireless sensor networks in the context of industrial automation, habitat monitoring, home automation, agriculture, etc. Wireless sensor network is a new technology currently adopted in various applications. Currently, there are a large number of researches going on and this motivates us to organize this special session to provide researchers the opportunity of gathering and sharing their latest knowledge with other researchers and scientific communities within the ICIT 2019.

Topics of interest include, but are not limited to:
- Industrial wireless sensor platform design
- Low-level design challenges in industrial environments
- WSN hardware/software standards
- Hardware designs/software for data acquisition/storage/visualisation
- Communication Technologies: LoRa, Wireless HART, ZigBee /802.15.4, IEEE 1451, 6LoWPAN, IPv4, IPv6 and BLE
- Communication issues in industrial environments
- WSN cloud computing and distributed control algorithms
- Practical deployment and prototype systems for experimental, proof of concept and field trials

**Accepted papers will be published in an IEEE proceedings volume and will be also submitted for the International Publication in *IEEEExplore***